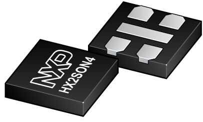

SOT2159-1

HX2SON4, thermal enhanced super thin small outline package, no leads, 4 terminals, 0.65 mm pitch, 1.6 mm x 1.6 mm x 0.32 mm body

19 January 2022 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HX2SON4
Package style descriptive code	X2SON (super thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	29-11-2021
Manufacturer package code	98ASA01843D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	1.6	-	mm
package width	-	1.6	-	mm
seated height	0.3	0.32	0.33	mm
actual quantity of termination	-	4	-	

2 Package outline

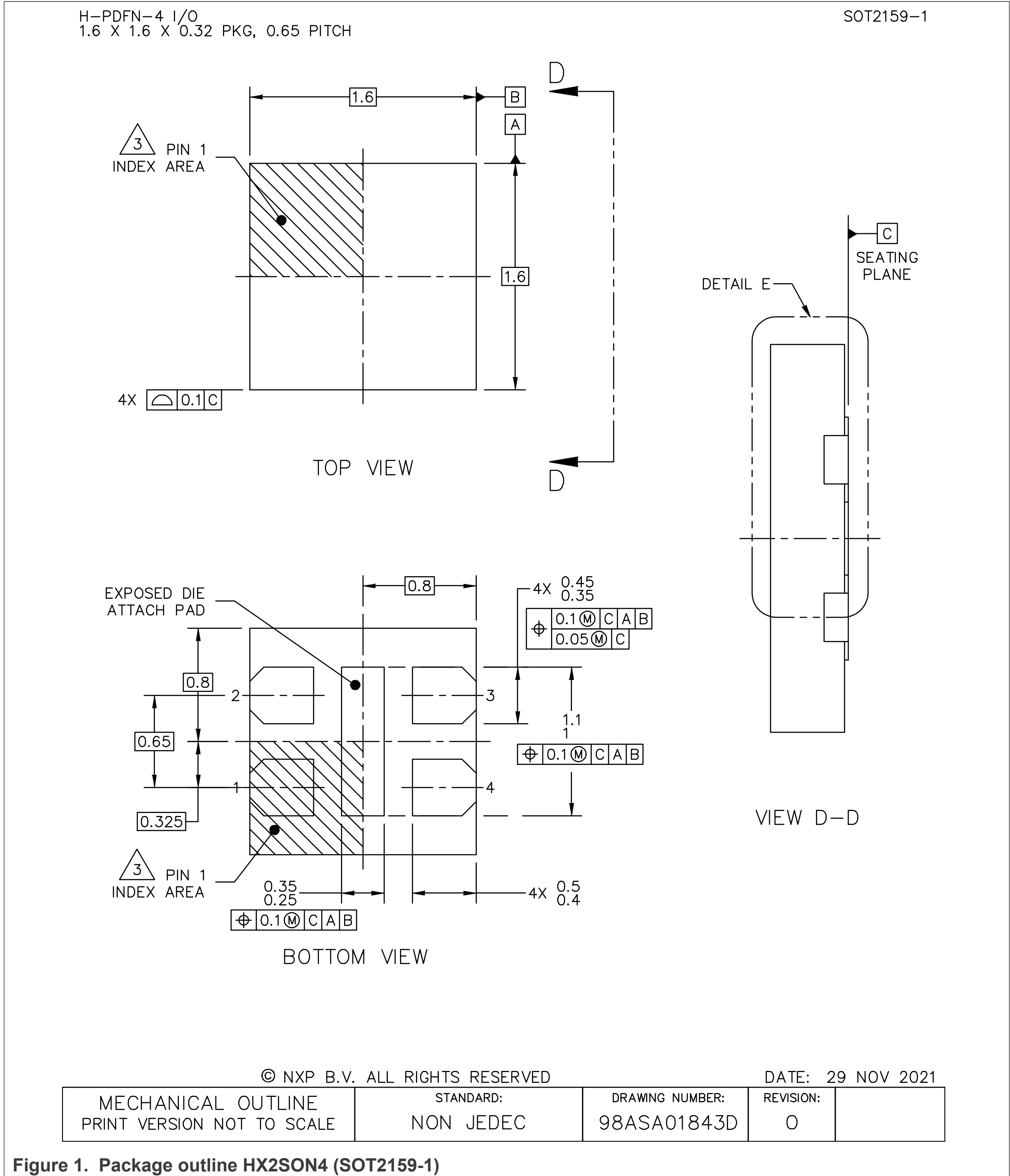

Figure 1. Package outline HX2SON4 (SOT2159-1)

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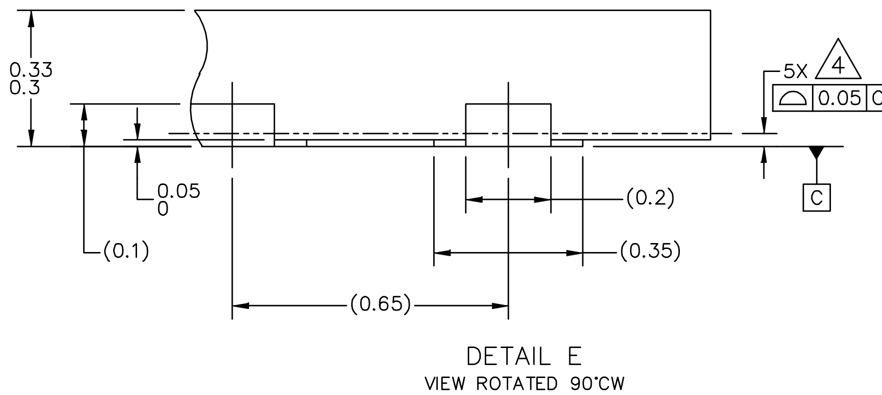
H-PDFN-4 I/O
1.6 X 1.6 X 0.32 PKG, 0.65 PITCH

SOT2159-1



DETAIL E
VIEW ROTATED 90°CW

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DATE: 29 NOV 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01843D	REVISION: 0	

Figure 2. Package outline detail E of HX2SON4 (SOT2159-1)

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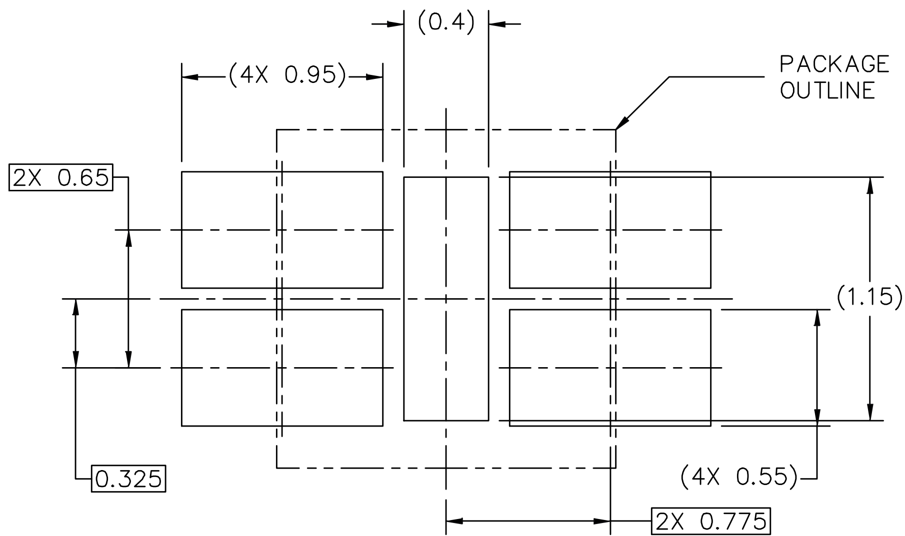
3 Soldering

H-PDFN-4 I/O
1.6 X 1.6 X 0.32 PKG, 0.65 PITCH

SOT2159-1



PCB DESIGN GUIDELINES
RECOMMENDED SOLDER MASK OPENING PATTERN

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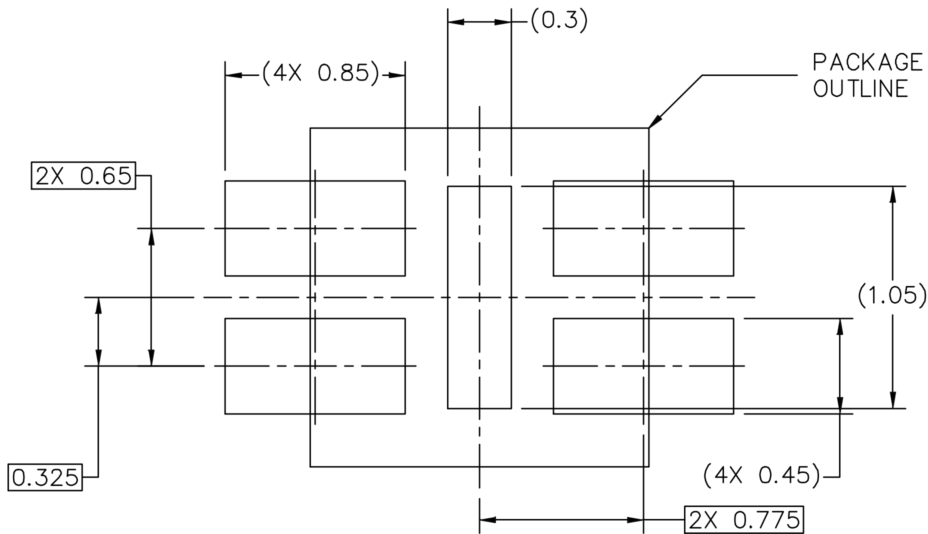
MECHANICAL OUTLINE	STANDARD:	DRAWING NUMBER:	REVISION:	
PRINT VERSION NOT TO SCALE	NON JEDEC	98ASA01843D	0	

Figure 3. Reflow soldering footprint part1 for HX2SON4 (SOT2159-1)

H–PDFN–4 I/O
1.6 X 1.6 X 0.32 PKG, 0.65 PITCH

SOT2159–1



PCB DESIGN GUIDELINES
RECOMMENDED I/O PADS AND SOLDERABLE AREA

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Figure 4. Reflow soldering footprint part2 for HX2SON4 (SOT2159-1)

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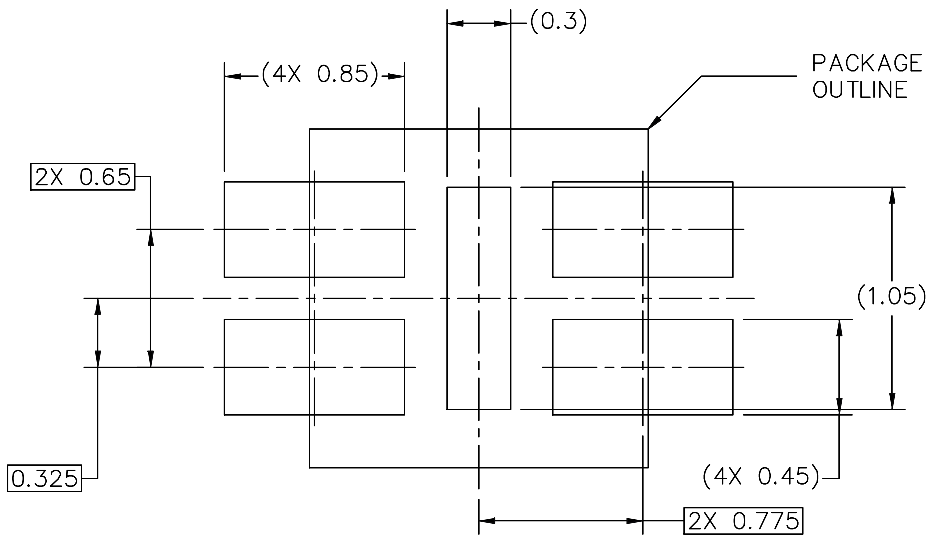
H-PDFN-4 I/O
1.6 X 1.6 X 0.32 PKG, 0.65 PITCH

SOT2159-1



RECOMMENDED STENCIL THICKNESS 0.125 OR 0.15

PCB DESIGN GUIDELINES – RECOMMENDED SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HX2SON4 (SOT2159-1)

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H-PDFN-4 I/O
1.6 X 1.6 X 0.32 PKG, 0.65 PITCH

SOT2159-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.15 MM.

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DATE: 29 NOV 2021

MECHANICAL OUTLINE	STANDARD:	DRAWING NUMBER:	REVISION:	
PRINT VERSION NOT TO SCALE	NON JEDEC	98ASA01843D	0	

Figure 6. Package outline note HX2SON4 (SOT2159-1)

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4 Legal information

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Date of release: 19 January 2022